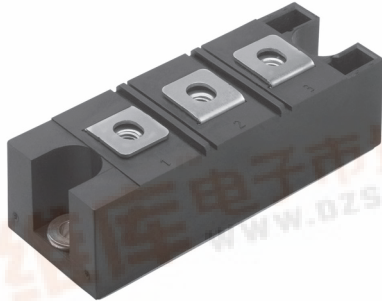




# VSKDU162/12PbF

Vishay High Power Products

## HEXFRED® Ultrafast Diodes, 100 A (New INT-A-PAK™ Power Modules)



New INT-A-PAK™

### FEATURES

- Electrically isolated: DBC base plate
- 3500 V<sub>RMS</sub> isolating voltage
- Standard JEDEC package
- Simplified mechanical designs, rapid assembly
- High surge capability
- Large creepage distances
- UL E78996 approved 
- Case style New INT-A-PAK
- Totally lead (Pb)-free
- Designed and qualified for industrial level



RoHS  
COMPLIANT

### PRODUCT SUMMARY

$I_{F(AV)}$	100 A
$V_{FM}$ (typical) at $I_C = 100$ A, 25 °C	2.5 V

### MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV) \text{ rect}}$		100	A
	$T_C$	88	°C
$t_{rr}$		200	ns
$V_{RRM}$		1200	V
$T_J, T_{Stg}$		- 40 to 150	°C

### ELECTRICAL SPECIFICATIONS

#### VOLTAGE RATINGS

TYPE NUMBER	VOLTAGE CODE	$V_{RRM}$ , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	$V_{RSM}$ , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V
VSKDU162/12PbF	12	1200	1250

#### FORWARD CONDUCTION

PARAMETER	SYMBOL	TEST CONDITIONS	TYP.	MAX.	UNITS
Maximum average forward current at case temperature	$I_{F(AV)}$	Rectangular conduction, 50 % duty cycle	-	100	A
			-	88	°C
Forward voltage drop	$V_{FM}$	$I_F = 100$ A, $T_J = 25$ °C, $t_p = 400$ μs square wave	2.5	3.2	V
		$I_F = 160$ A, $T_J = 25$ °C, $t_p = 400$ μs square wave	2.9	3.9	
Reverse recovery time	$t_{rr}$	$I_F = 160$ A, $T_J = 25$ °C, - $di/dt = 200$ A/μs, $V_R = 200$ V	150	200	ns
Reverse recovery charge	$Q_{rr}$		2000	2400	nC
Reverse recovery current	$I_{REC}$		20	22	A
Maximum forward voltage drop	$dI_{(rec)M}/dt$		-	300	A/μs



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<b>BLOCKING</b>				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum peak reverse leakage current	$I_{RRM}$	$T_J = 150\text{ °C}$	30	mA
RMS insulation voltage	$V_{INS}$	50 Hz, circuit to base, all terminals shorted, $t = 1\text{ s}$	3500	V

<b>THERMAL AND MECHANICAL SPECIFICATIONS</b>				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction operating and storage temperature range	$T_J, T_{Stg}$		- 40 to 150	°C
Maximum thermal resistance, junction to case per junction	$R_{thJC}$	DC operation	0.18	K/W
Typical thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth and greased	0.05	
Mounting torque $\pm 10\%$ to heatsink busbar		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow the spread of the compound.	4 to 6	Nm
Approximate weight			200	g
			7.1	oz.
Case style			New INT-A-PAK	



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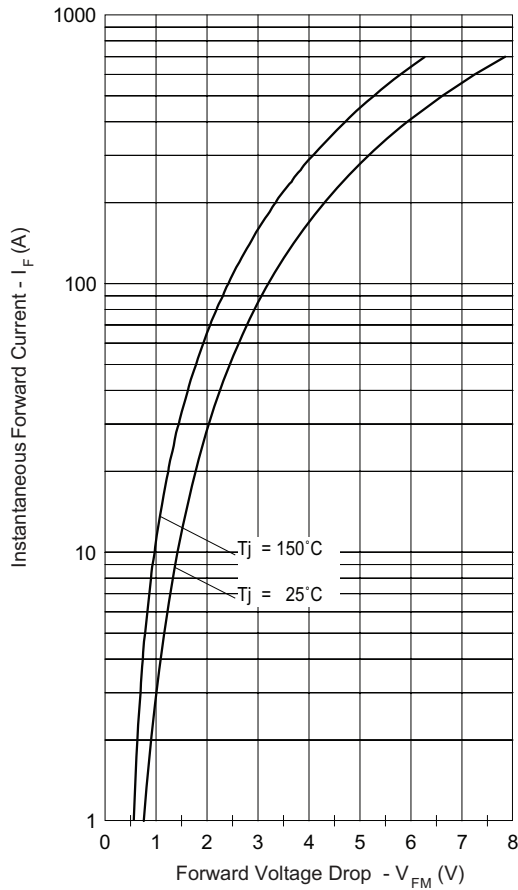


Fig. 1 - Maximum Forward Voltage Drop Characteristics

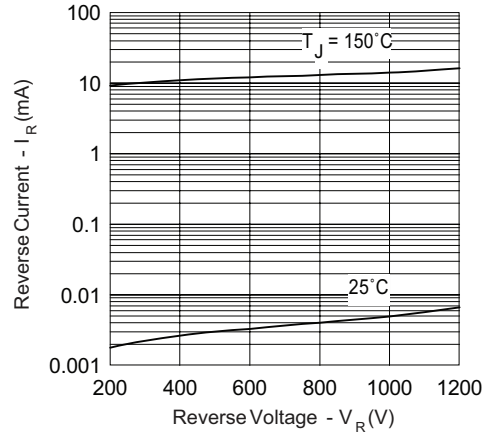


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

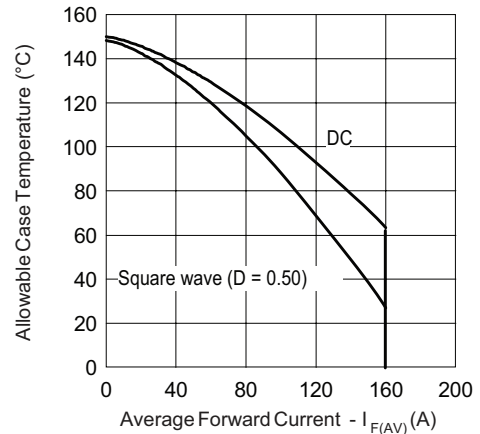


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

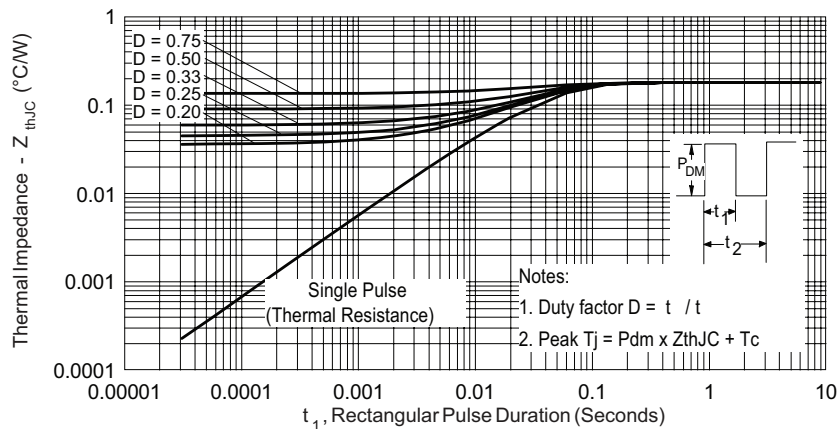


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

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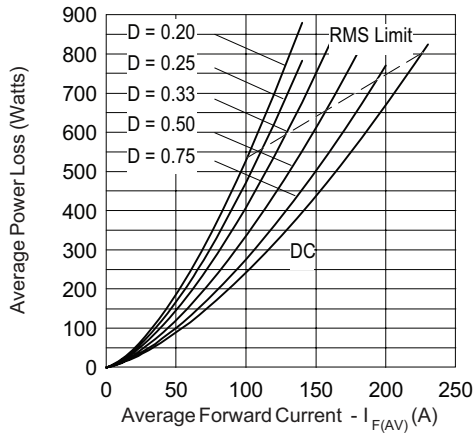


Fig. 5 - Forward Power Loss Characteristics

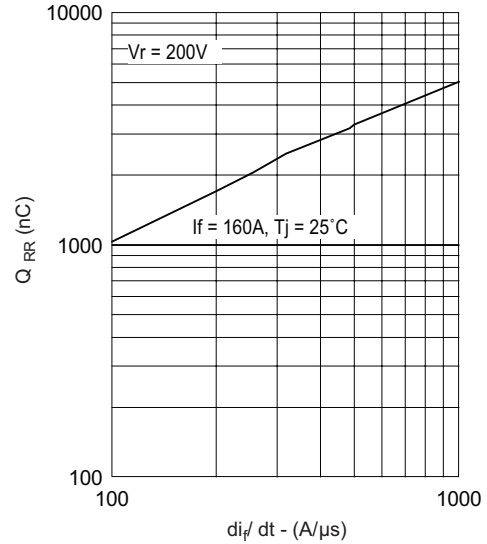


Fig. 7 - Typical Reverse Recovery Charge vs.  $di_f/dt$  (Per Leg)

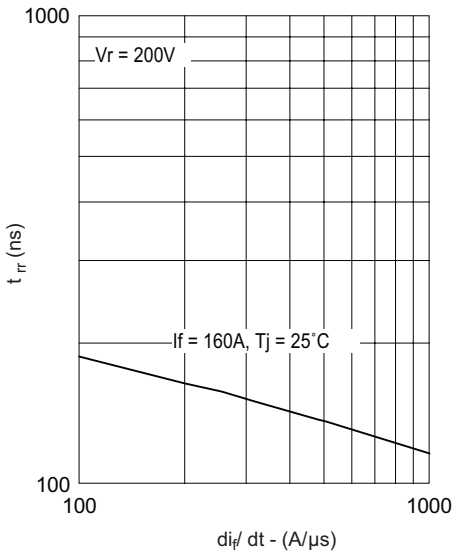


Fig. 6 - Typical Reverse Recovery Time vs.  $di_f/dt$  (Per Leg)

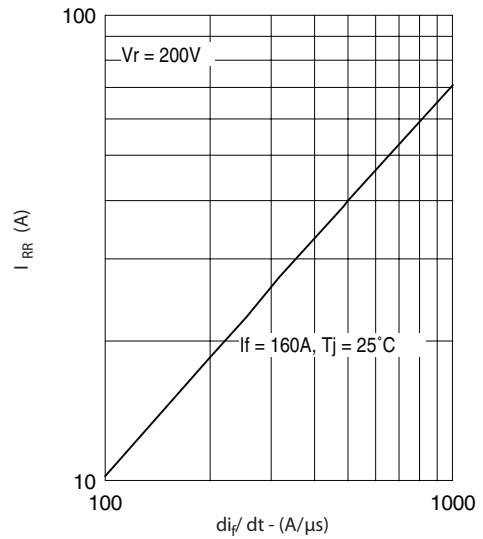


Fig. 8 - Typical Reverse Recovery Current vs.  $di_f/dt$  (Per Leg)



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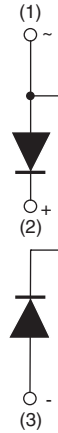
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## ORDERING INFORMATION TABLE

Device code	<b>VS</b>	<b>K</b>	<b>DU</b>	<b>162</b>	<b>/</b>	<b>12</b>	<b>PbF</b>
	①	②	③	④		⑤	⑥

- 1** - Vishay HPP
- 2** - K = New INT-A-PAK module
- 3** - DU = HEXFRED® ultrafast diode
- 4** - Current rating
- 5** - Voltage rating (12 = 1200 V)
- 6** - PbF = Lead (Pb)-free

## CIRCUIT CONFIGURATION



### LINKS TO RELATED DOCUMENTS

Dimensions

<http://www.vishay.com/doc?95254>



### Disclaimer

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